Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: <u>ti.com/support</u>

Form/Declaration Type: Distribute - RoHS and IEC 62474 DB

Created on: **06/11/2022**

Details for "TPS73719QDRBRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS73719QDRBRQ1	NIPDAU	Level-3-260C-168 HR	TI MALAYSIA A/T	DRB 8	3.0x3.0x0.9	21.9

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Indium	7440-74-6	0.000002	0.001309	13	0.000009	0
Precious Metals	Gold	7440-57-5	0.152787	99.997382	999974	0.698696	6987
Precious Metals	Silver	7440-22-4	0.000002	0.001309	13	0.000009	0
Sub-Total			0.152791	100	1000000	0.698714	6987
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.00508	2.000102	20001	0.023231	232
Precious Metals	Silver	7440-22-4	0.175251	68.999988	690000	0.801424	8014
Thermoplastics	Ероху	85954-11-6	0.073656	28.999909	289999	0.336829	3368
Sub-Total			0.253987	100	1000000	1.161484	11615
Lead Frame	•	•					
Copper and Its Alloys	Copper	7440-50-8	8.425333	99.249994	992500	38.529085	385291
Other Nonferrous Metals and Alloys	Chromium	7440-47-3	0.022071	0.259995	2600	0.100931	1009
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.021223	0.250006	2500	0.097053	971
Zinc and Its Alloys	Zinc	7440-66-6	0.020374	0.240005	2400	0.09317	932
Sub-Total			8.489001	100	1000000	38.820239	388202
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.145534	95.120261	951203	0.665528	6655
Precious Metals	Gold	7440-57-5	0.001193	0.779739	7797	0.005456	55
Precious Metals	Palladium	7440-05-3	0.006273	4.1	41000	0.028686	287
Sub-Total			0.153	100	1000000	0.69967	6997
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	10.849461	90.499998	905000	49.614633	496146
Other Plastics and Rubber	Carbon Black	1333-86-4	0.059942	0.500002	5000	0.274115	2741
Thermoplastics	Ероху	85954-11-6	1.078952	9	90000	4.934052	49341
Sub-Total			11.988355	100	1000000	54.8228	548228
Semiconductor Device	•	•			•		
Ceramics / Glass	Doped Silicon	7440-21-3	0.830328	100	1000000	3.797094	37971
Sub-Total			0.830328	100	1000000	3.797094	37971
Total			21.867462			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

Important Part Information

See Glossary of Terms for more details.

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/11/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.